



Material Content Data Sheet



Sales Product Name		IFX25001TF V33		Issued		27. September 2017		
MA#		MA000713442						
Package		PG-TO252-3-11		Weight*		379.51 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.945	0.78	0.78	7760	7760
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		567	
	inorganic material	phosphorus	7723-14-0	0.065	0.02		170	
	non noble metal	copper	7440-50-8	215.017	56.65	56.73	566561	567298
wire	non noble metal	aluminium	7429-90-5	0.117	0.03	0.03	308	308
encapsulation	organic material	carbon black	1333-86-4	0.267	0.07		704	
	plastics	epoxy resin	-	12.285	3.24		32371	
	inorganic material	silicondioxide	60676-86-0	120.984	31.88	35.19	318789	351864
leadfinish	non noble metal	tin	7440-31-5	3.740	0.99	0.99	9855	9855
plating	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	239	240
	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
solder	noble metal	silver	7440-22-4	0.115	0.03		302	
	non noble metal	tin	7440-31-5	0.092	0.02		242	
	non noble metal	lead	7439-92-1	4.377	1.15	1.20	11533	12077
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		51	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	copper	7440-50-8	19.177	5.05	5.06	50532	50598
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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